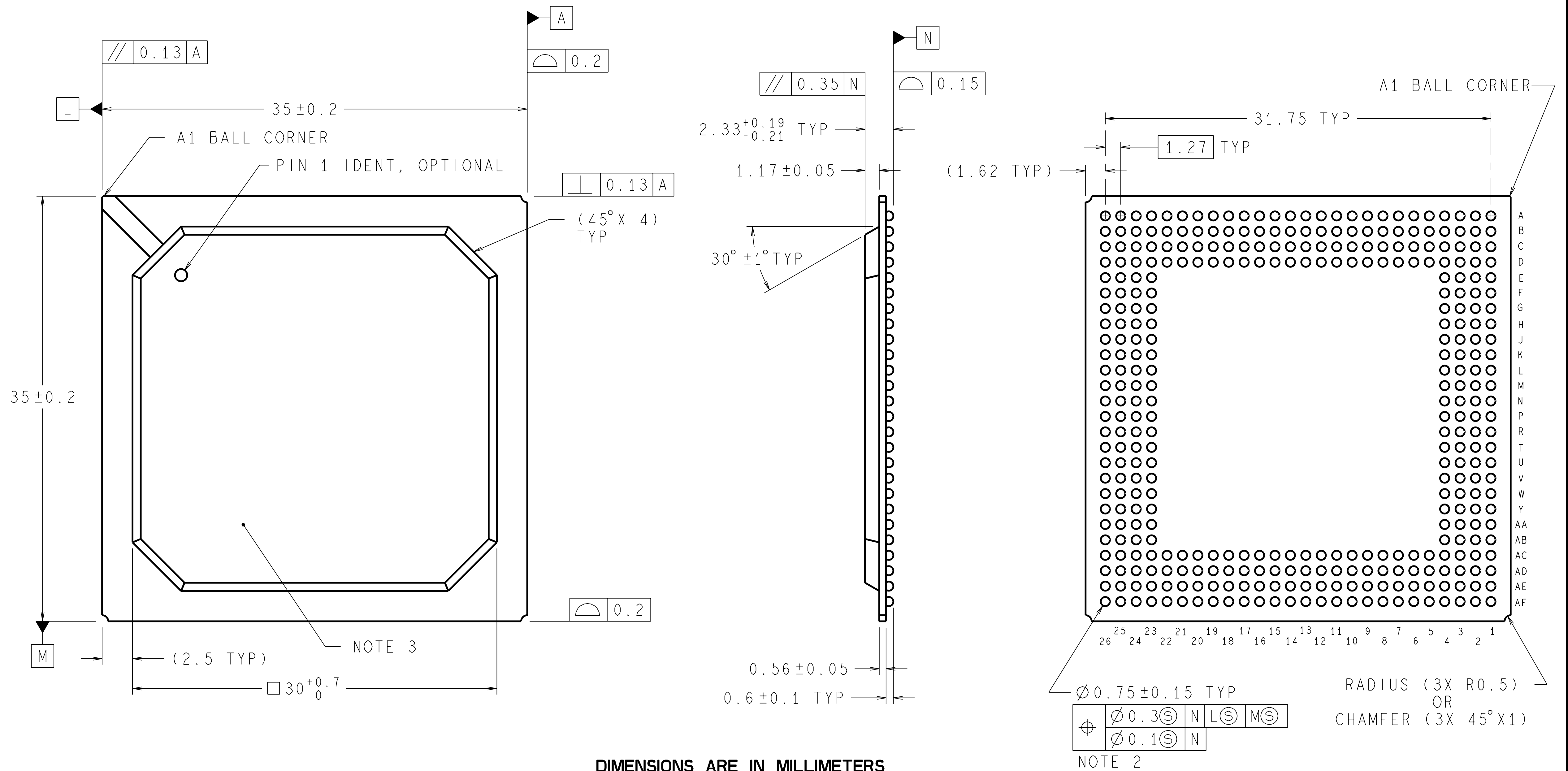
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11627	12/20/1996	MS/SM
B	REVISE NOTES 3 & 4.	12342	11/15/1999	MS/MJL
C	REMOVE NOTE 5; ADD OR (3X 45° X1) TO CHAMFER CORNER.	142	09/19/2000	MS/CD



NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION, AND MOLD EJECTOR PIN MARKS AT EACH CORNER OF MOLDED PACKAGE SURFACE.
4. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27 PITCH, DATED JUNE 1997.

APPROVALS	DATE
DRAWN MARTA SUCHY	12/20/1996
DFTG. CHK. THANH LEQUANG	09/19/2000
ENGR. CHK. CORNEL DEVERA	09/19/2000

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

PBGA,
35 X 35 X 2.33mm,
352 BALL, 1.27mm PITCH

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-UCE352A	C

DO NOT SCALE DRAWING — SHEET 1 of 1